

Title (en)
MEMS PACKAGING

Title (de)
MEMS-SCHALTER UND DEREN VERPACKUNG

Title (fr)
COMMUTATEURS MEMS ET LEUR CONDITIONNEMENT

Publication
EP 2499648 B1 20141029 (EN)

Application
EP 10775878 A 20101110

Priority

- GB 0919724 A 20091111
- EP 09275108 A 20091111
- GB 201016803 A 20101006
- GB 2010051874 W 20101110
- EP 10775878 A 20101110

Abstract (en)
[origin: WO2011058354A1] A packaged RF MEMS device comprising: an RF MEMS device, a substrate upon which the RF MEMS device is mounted, a cover mounted on the substrate, the cover comprising a cavity for containing the RF MEMS device, the cover and substrate thereby defining a cover-to-substrate interface and a cover-to-substrate interface boundary, and at least one electrically conductive path extending between the RF MEMS device and a peripheral surface of the packaged MEMS device.

IPC 8 full level
H01H 59/00 (2006.01)

CPC (source: EP)
H01H 59/0009 (2013.01); **H01H 2001/0084** (2013.01)

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)
WO 2011058354 A1 20110519; EP 2499648 A1 20120919; EP 2499648 B1 20141029

DOCDB simple family (application)
GB 2010051874 W 20101110; EP 10775878 A 20101110